Patent Application No. 10/812,734 Customer Number: 42717

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Shau-Lin Shue, et al.

Docket No.:

24061.587

(TSMC2000-0101)

Serial No.:

10/812,734

§

Examiner:

Bradley Smith

Filing Date:

March 30, 2004

Art Unit:

2824

For:

Method for Forming a Self-

Passivated Copper Interconnect

Structure

Conf. No.:

4809

RESPONSE TO RESTRICTION REQUIREMENT

Mail Stop: Amendment Commissioner for Patents

PO Box 1450

Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action mailed August 31, 2004, applicant hereby elects, Group II, Claims 32-56, which is drawn to a device.

Applicant's election is made with traverse on the grounds that the embodiments delineated by the examiner are not patentably distinct and therefore constitute a single invention concept.

An early action on the merits is respectfully requested.

Respectfully submitted,

David M. O'Dell

Reg. No. 42,044

Date: 9-30-04

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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Mail Stop: Amendment, Commissioner For Patents, PO Box 1450, Alexandria, VA 22313-1450 on the date below.

Name

Date